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CONFIRMATION NO. 2572

SERIAL NUMBER 10/632,552	FILING DATE 08/02/2003 RULE	CLASS 257	GROUP ART UNIT 2815	ATTORNEY DOCKET NO. CPAC 1017-5
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APPLICANTS

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** CONTINUING DATA *****

This appln claims benefit of 60/411,590 09/17/2002

yes C.C.

** FOREIGN APPLICATIONS *****

None C.C.

IF REQUIRED, FOREIGN FILING LICENSE GRANTED

** 10/30/2003

Foreign Priority claimed	<input type="checkbox"/> yes <input checked="" type="checkbox"/> no	STATE OR COUNTRY	SHEETS	TOTAL	INDEPENDENT
35 USC 119 (a-d) conditions met	<input type="checkbox"/> yes <input checked="" type="checkbox"/> no <input type="checkbox"/> Met after Allowance	DRAWING	CLAIMS	CLAIMS	
Verified and Acknowledged Examiner's Signature	<i>Christina</i>	CA	7	36	2

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TITLE

Semiconductor multi-package module having package stacked over die-up flip chip ball grid array package and having wire bond interconnect between stacked packages

FILING FEE	FEES: Authority has been given in Paper No. _____ to charge/credit DEPOSIT ACCOUNT No. _____ for following:	<input type="checkbox"/> All Fees <input type="checkbox"/> 1.16 Fees (Filing) <input type="checkbox"/> 1.17 Fees (Processing Ext. of time) <input type="checkbox"/> 1.18 Fees (Issue) <input type="checkbox"/> Other _____ <input type="checkbox"/> Credit
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